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EE COMCAS 201

International Conference on Microwaves, Communications, Antennas and Electronic Systems David Intercontinental Hotel ■13-15 November 2017 ■ Tel Aviv, Israel

Call for Papers

COMCAS 2017 continues the tradition of providing an international, multidisciplinary forum for the exchange of ideas, research results, and industry experience in the areas of microwave/RF/mm-wave engineering, communications, antennas, solid state circuits, electronic devices, engineering in medicine, radar, sonar and electronic systems.

The technical program includes invited talks by international experts and contributed papers and will be complemented by a large industrial exhibition.

Important Deadlines

Summary Submission:

April 20, 2017

Acceptance Notification: July 5, 2017

Full Paper Submission:

September 4, 2017

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Papers are solicited in a wide range of topics:

Communications and Sensors

5G systems & millimeter wave propagation Cognitive Radio & Spectral Sharing Communications Security First Responder/Military Communications

Green Communication Internet of Things

Long Range Low Power Networks Micro/Pico/Femtocell Devices and Systems

MIMO Antenna Systems for Communications Modulation & Signal Processing Technologies On-Body and Short Range Communications Radio over Fiber & Optical/Wireless Convergence

Sensor Networks and Technologies Software-Defined Radio & Multiple Access Space-Time Coding and Systems

Antennas, Propagation, and Scattering

Smart Antennas, Beamforming and MIMO Wave Propagation and Channel Modeling Wave Scattering and RCS NanoEM, Plasmonics, and Applications Metamaterials, FSS and EBG EM Field Theory and Numerical Techniques EM Interference & Compatibility, SI Spectrum Management and Monitoring ELF, RF, µWave, mmW and THz Measurements

Signal Processing (SP) and Imaging

Microwave Imaging and Tomography Acoustic/Sonar Imaging and Techniques Radar SP and Imaging, SAR, ATR MIMO SP for Radar Ground and Foliage Penetration Systems Signal Acquisition and Sensor Management DF, Emitter Location, Elint, Array Processing Target Detection, Identification and Tracking Data Fusion

Time Domain and UWB SP

RF/MW Devices and Circuits, RFICs

Solid-State Devices, RFICs µWave, mmW and Sub-mmW Circuits/Technologies Nano and THz Devices/Technologies

Microwave Photonics

Passive Components and Circuits Filters and Multiplexers

Ferroelectrics, RF MEMS, MOEMS, and NEMS

Active Devices and Circuits RF Power Amplifiers and Devices

Tunable and Reconfigurable Circuits/Systems

Analog/Digital/Mixed RF Circuits Circuit Theory, Modeling and Applications

Interconnects, Packaging and MCM CAD Techniques for Devices and Circuits

Emerging Technologies

Thermal Management for Devices

Microwave Systems, Radar, Acoustics

Aeronautical and Space Applications RFID Devices/Systems/Applications Automotive/Transportation Radar & Communications Environmentally Sensitive ("Green") Design UWB and Multispectral Technologies & Systems **Emerging System Architectures** Modelling Techniques for RF Systems

Radar Techniques, Systems and Applications Sonar Systems and Applications

Wireless Power Transfer & Energy Harvesting Terahertz Systems

Biomedical Engineering

Advances in MRI: Technology, Systems and Applications Medical RF, MW & MMW Applications and Devices Medical Imaging and Image Processing

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All submitted papers will be peer reviewed. Accepted papers will be published in the COMCAS 2017 Proceedings, which will be submitted for inclusion to IEEE Xplore®.

For author's instructions and further information, see www.comcas.org.













